

MPS2907A

Preferred Device

General Purpose Transistors

PNP Silicon

Features

- Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	-60	Vdc
Collector-Base Voltage	V_{CBO}	-60	Vdc
Emitter-Base Voltage	V_{EBO}	-5.0	Vdc
Collector Current - Continuous	I_C	-600	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	625 5.0	mW mW/ $^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	$^\circ\text{C}/\text{W}$

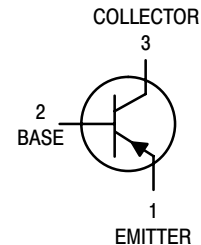
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

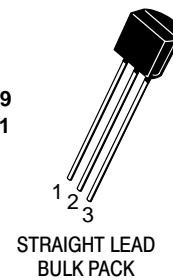


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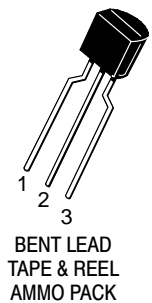
<http://onsemi.com>



TO-92
CASE 29
STYLE 1

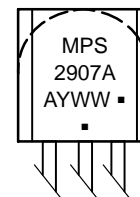


STRAIGHT LEAD
BULK PACK



BENT LEAD
TAPE & REEL
AMMO PACK

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

MPS2907A

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage (Note 1) (I _C = –10 mA _{dc} , I _B = 0)	V _{(BR)CEO}	–60	–	V _{dc}	
Collector–Base Breakdown Voltage (I _C = –10 μA _{dc} , I _E = 0)	V _{(BR)CBO}	–60	–	V _{dc}	
Emitter–Base Breakdown Voltage (I _E = –10 μA _{dc} , I _C = 0)	V _{(BR)EBO}	–5.0	–	V _{dc}	
Collector Cutoff Current (V _{CE} = –30 V _{dc} , V _{EB(off)} = –0.5 V _{dc})	I _{CEX}	–	–50	nA _{dc}	
Collector Cutoff Current (V _{CB} = –50 V _{dc} , I _E = 0) (V _{CB} = –50 V _{dc} , I _E = 0, T _A = 150°C)	I _{CBO}	–	–0.01 –10	μA _{dc}	
Base Current (V _{CE} = –30 V _{dc} , V _{EB(off)} = –0.5 V _{dc})	I _B	–	–50	nA _{dc}	
ON CHARACTERISTICS					
DC Current Gain (I _C = –0.1 mA _{dc} , V _{CE} = –10 V _{dc}) (I _C = –1.0 mA _{dc} , V _{CE} = –10 V _{dc}) (I _C = –10 mA _{dc} , V _{CE} = –10 V _{dc}) (I _C = –150 mA _{dc} , V _{CE} = –10 V _{dc}) (Note 1) (I _C = –500 mA _{dc} , V _{CE} = –10 V _{dc}) (Note 1)	h _{FE}	75 100 100 100 50	– – – 300 –	–	
Collector–Emitter Saturation Voltage (Note 1) (I _C = –150 mA _{dc} , I _B = –15 mA _{dc}) (I _C = –500 mA _{dc} , I _B = –50 mA _{dc})	V _{CE(sat)}	– –	–0.4 –1.6	V _{dc}	
Base–Emitter Saturation Voltage (Note 1) (I _C = –150 mA _{dc} , I _B = –15 mA _{dc}) (I _C = –500 mA _{dc} , I _B = –50 mA _{dc})	V _{BE(sat)}	– –	–1.3 –2.6	V _{dc}	
SMALL–SIGNAL CHARACTERISTICS					
Current–Gain–Bandwidth Product (Notes 1 and 2), (I _C = –50 mA _{dc} , V _{CE} = –20 V _{dc} , f = 100 MHz)	f _T	200	–	MHz	
Output Capacitance (V _{CB} = –10 V _{dc} , I _E = 0, f = 1.0 MHz)	C _{obo}	–	8.0	pF	
Input Capacitance (V _{EB} = –2.0 V _{dc} , I _C = 0, f = 1.0 MHz)	C _{ibo}	–	30	pF	
SWITCHING CHARACTERISTICS					
Turn–On Time	(V _{CC} = –30 V _{dc} , I _C = –150 mA _{dc} , I _{B1} = –15 mA _{dc}) (Figures 1 and 5)	t _{on}	–	45	ns
Delay Time		t _d	–	10	ns
Rise Time		t _r	–	40	ns
Turn–Off Time	(V _{CC} = –6.0 V _{dc} , I _C = –150 mA _{dc} , I _{B1} = I _{B2} = 15 mA _{dc}) (Figure 2)	t _{off}	–	100	ns
Storage Time		t _s	–	80	ns
Fall Time		t _f	–	30	ns

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
2. f_T is defined as the frequency at which |h_{fe}| extrapolates to unity.

MPS2907A

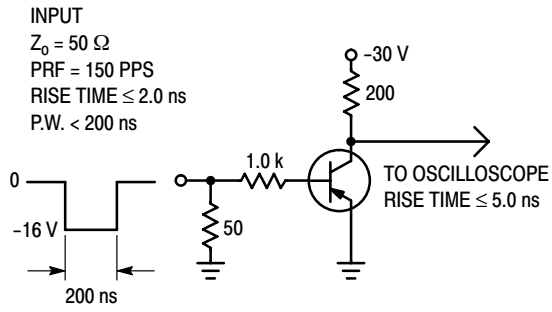


Figure 1. Delay and Rise Time Test Circuit

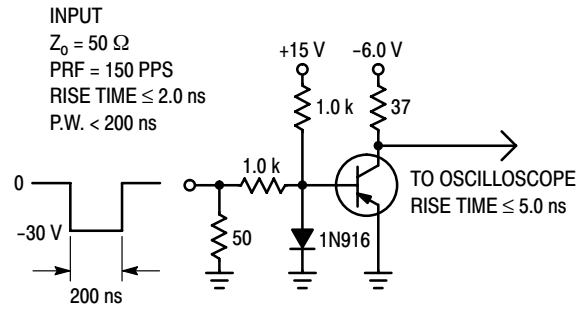
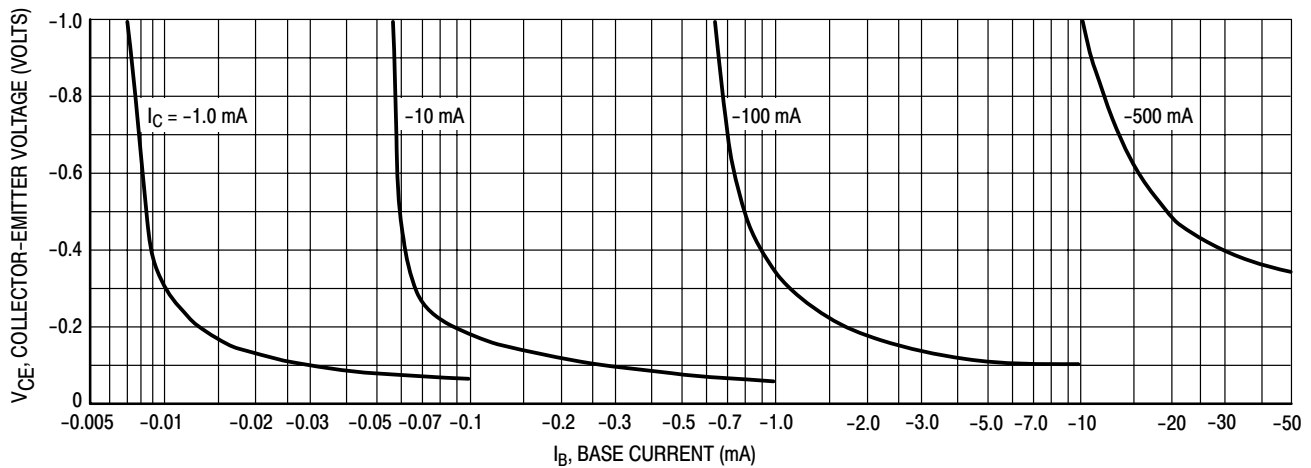
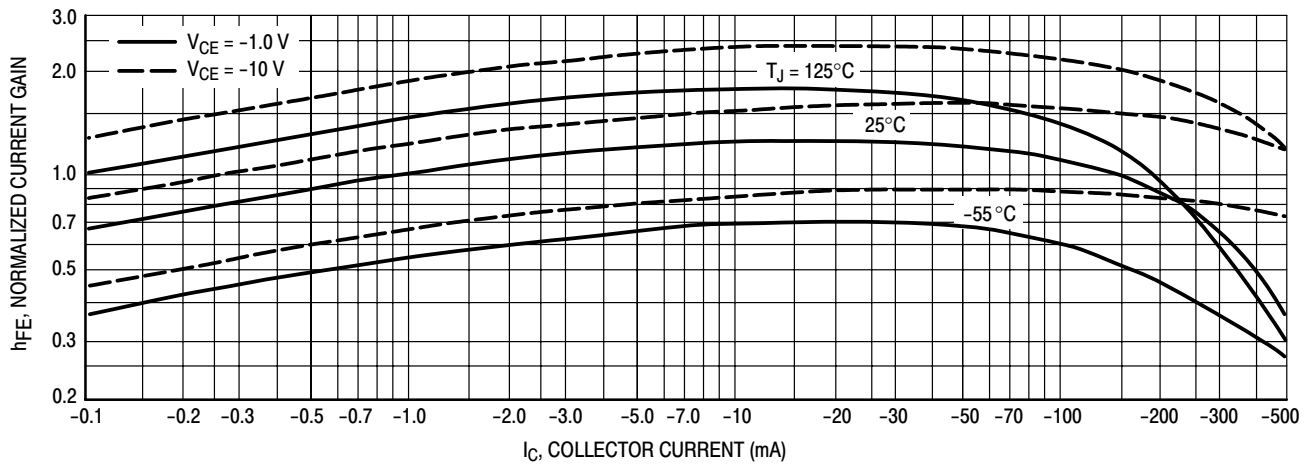


Figure 2. Storage and Fall Time Test Circuit

TYPICAL CHARACTERISTICS



MPS2907A

ORDERING INFORMATION

Device	Package	Shipping†
MPS2907A	TO-92	5000 Units / Bulk
MPS2907AG	TO-92 (Pb-Free)	
MPS2907ARLG	TO-92 (Pb-Free)	2000 / Tape & Reel
MPS2907ARLRA	TO-92	
MPS2907ARLRAG	TO-92 (Pb-Free)	
MPS2907ARLRPG	TO-92 (Pb-Free)	2000 / Ammo Pack

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

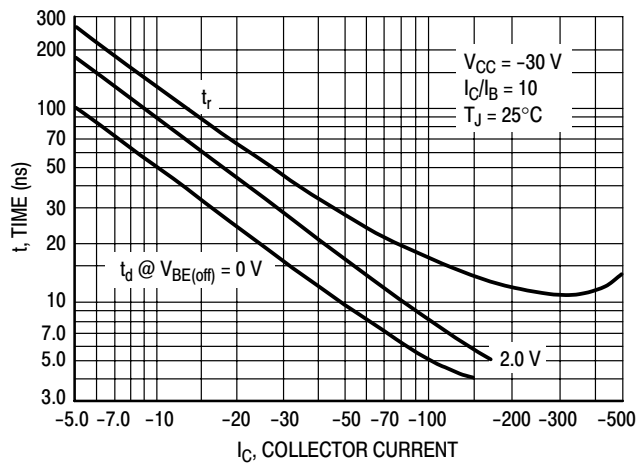


Figure 5. Turn-On Time

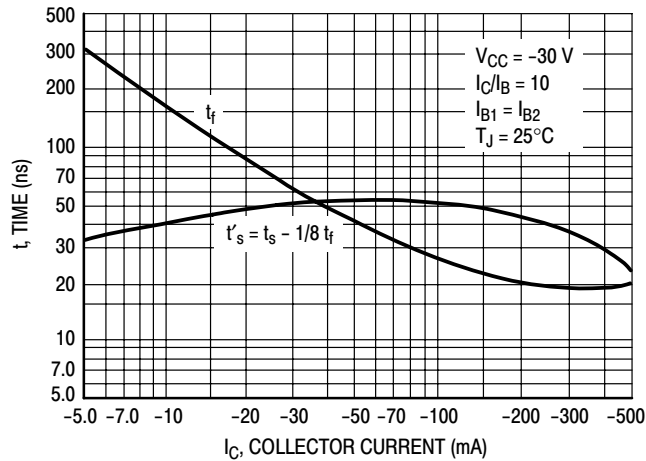


Figure 6. Turn-Off Time

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TYPICAL SMALL-SIGNAL CHARACTERISTICS

NOISE FIGURE

$V_{CE} = 10 \text{ Vdc}$, $T_A = 25^\circ\text{C}$

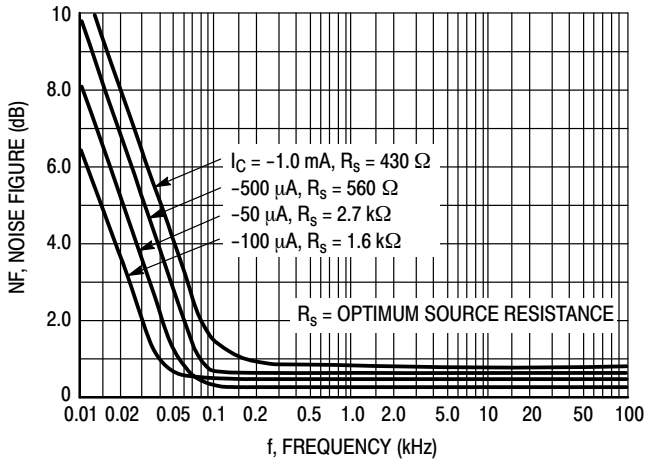


Figure 7. Frequency Effects

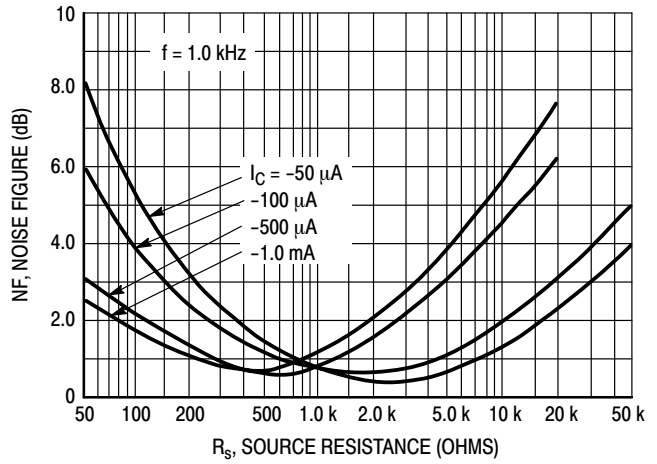


Figure 8. Source Resistance Effects

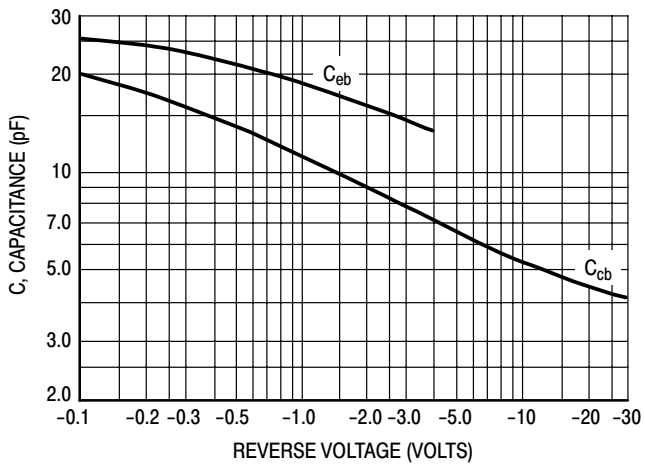


Figure 9. Capacitances

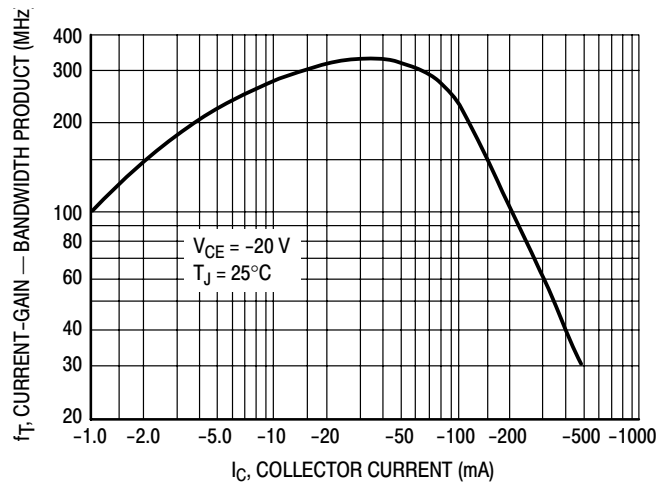


Figure 10. Current-Gain — Bandwidth Product

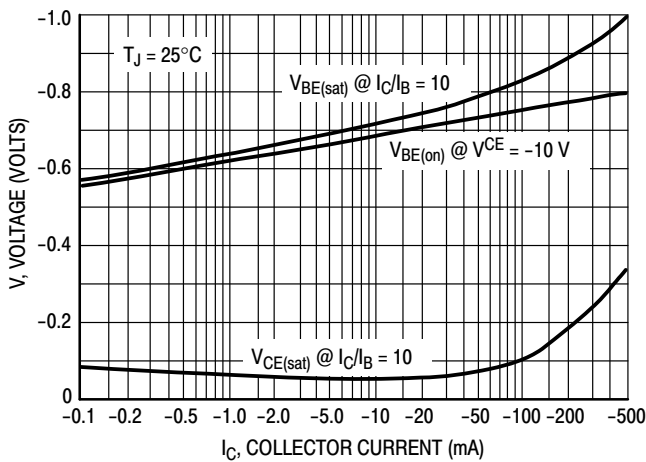


Figure 11. "On" Voltage

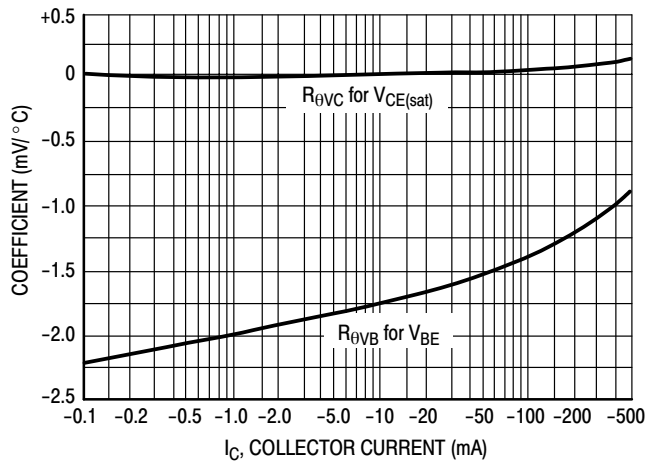
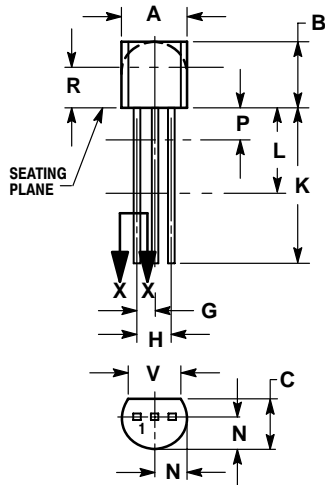


Figure 12. Temperature Coefficients

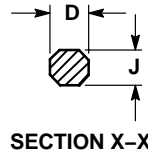
MPS2907A

PACKAGE DIMENSIONS

TO-92 (TO-226)
CASE 29-11
ISSUE AM



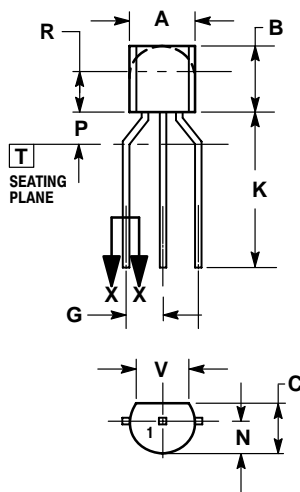
STRAIGHT LEAD
BULK PACK



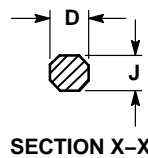
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---



BENT LEAD
TAPE & REEL
AMMO PACK




NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

STYLE 1:

1. EMITTER
2. BASE
3. COLLECTOR

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